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Bib Data Sheet

SERIAL NUMBER 09/945,241	FILING DATE 08/31/2001 RULE	CLASS 257	GROUP ART UNIT 2815	ATTORNEY DOCKET NO. 9319I-000277
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APPLICANTS

Fumiaki Matsushima, Chino-shi, JAPAN;
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 Akira Makabe, Shiojin-shi, JAPAN;

** CONTINUING DATA *****

none

** FOREIGN APPLICATIONS *****

JAPAN 2000-267076 09/04/2000 *1m*

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 10/04/2001

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY JAPAN	SHEETS DRAWING 13	TOTAL CLAIMS 29	INDEPENDENT CLAIMS 4
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged	<i>1m</i> Examiner's Signature Initials				

ADDRESS

27572

TITLE

Method for forming a bump, semiconductor device and method of fabricating same, semiconductor chip, circuit board, and electronic instrument

FILING FEE RECEIVED 1116	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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